

Bill of Materials

Project Name:	10A DDR3 LV PSU for 5V input
Project File:	PMP10029RevA2.PrjPCB
PCB Rev:	A2
Schematic Rev:	A2
Assembly Variant:	None
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Quantity	Designator	Value	Description	PackageReference	PartNumber	Manufacturer
2	C1, C5	0.1uF	CAP, CERM, 0.1uF, 16V, +/-10%, X7R, 0402	0402	GRM155R71C104KA88D	MuRata
2	C2, C15	1uF	CAP, CERM, 1uF, 10V, +/-10%, X5R, 0402	0402	GRM155R61A105KE15D	MuRata
2	C3, C6	22uF	CAP, CERM, 22uF, 4V, +/-20%, X5R, 0603	0603	GRM188R60G226MEAOL	MuRata
1	C4	4.7uF	CAP, CERM, 4.7uF, 16V, +/-10%, X5R, 0603	0603	GRM188R61C475KAAJ	MuRata
3	C7, C13, C14	0.1uF	CAP, CERM, 0.1uF, 50V, +/-10%, X7R, 0603	0603	GCM188R71H104KA57D	MuRata
1	C8	1000pF	CAP, CERM, 1000pF, 50V, +/-10%, X7R, 0603	0603	GRM188R71H102KA01D	MuRata
2	C9, C11	22uF	CAP, CERM, 22uF, 25V, +/-10%, X7R, 1210	1210	GRM32ER71E226KE15L	MuRata
2	C10, C12	100uF	CAP, CERM, 100uF, 6.3V, +/-20%, X5R, 1210	1210	GRM32ER60J107ME20L	MuRata
1	D1	30V	Diode, Schottky, 30V, 3A, SMA	SMA	B330A-13-F	Diodes Inc.
2	J1, J2		Header, 100mil, 3x1, Tin plated, TH	Header, 3 PIN, 100mil, Tin	PEC03SAAN	Sullins Connector Solutions
4	J3, J4, J5, J6		Terminal Block, 6A, 3.5mm Pitch, 2-Pos, TH	7.0x8.2x6.5mm	ED555/2DS	On-Shore Technology
1	L1	680nH	Inductor, Shielded Drum Core, Ferrite, 680nH, 19A, 0.0017 ohm, SMD	WE-HCC-8X7	7443340068	Würth Elektronik eiSos
1	R1	10.0k	RES, 10.0k ohm, 1%, 0.063W, 0402	0402	CRCW040210K0FKED	Vishay-Dale
1	R2	30.1k	RES, 30.1k ohm, 1%, 0.063W, 0402	0402	CRCW040230K1FKED	Vishay-Dale
1	R3	14.0k	RES, 14.0k ohm, 1%, 0.063W, 0402	0402	CRCW040214K0FKED	Vishay-Dale
1	R4	10.0k	RES, 10.0k ohm, 1%, 0.1W, 0603	0603	CRCW060310K0FKEA	Vishay-Dale
1	R5	100k	RES, 100k ohm, 1%, 0.063W, 0402	0402	CRCW0402100KFKED	Vishay-Dale
1	R6	1.00k	RES, 1.00k ohm, 1%, 0.063W, 0402	0402	CRCW04021K00FKED	Vishay-Dale
2	R7, R8	3.32	RES, 3.32 ohm, 1%, 0.063W, 0402	0402	CRCW04023R32FKED	Vishay-Dale
2	R9, R11	0	RES, 0 ohm, 5%, 0.063W, 0402	0402	CRCW04020000Z0ED	Vishay-Dale
1	R10	1.00	RES, 1.00 ohm, 1%, 0.063W, 0402	0402	CRCW04021R00FKED	Vishay-Dale
1	R12	0.75	RES, 0.75 ohm, 1%, 0.5W, 1206	1206	CSR1206FKR750	Stackpole Electronics Inc
5	TP3, TP5, TP7, TP10, TP12	Black	Test Point, Miniature, Black, TH	Black Miniature Testpoint	5001	Keystone
3	TP6, TP9, TP11	Red	Test Point, Miniature, Red, TH	Red Miniature Testpoint	5000	Keystone
1	TP8	White	Test Point, Miniature, White, TH	White Miniature Testpoint	5002	Keystone
1	U1		Complete DDR2, DDR3, DDR3L, and LPDDR3 Memory Power Solution Synchronous Buck Controller, 2-A LDO, with Buffered Reference, RUK0020B	RUK0020B	TPS51716RUK	Texas Instruments
1	U2		Synchronous Buck NexFET Power Block, DQY0008A	DQY0008A	CSD87350Q5D	Texas Instruments

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